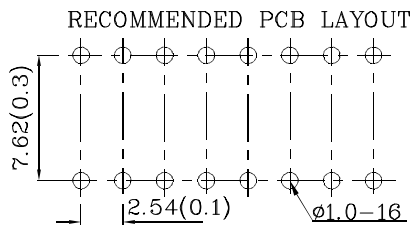
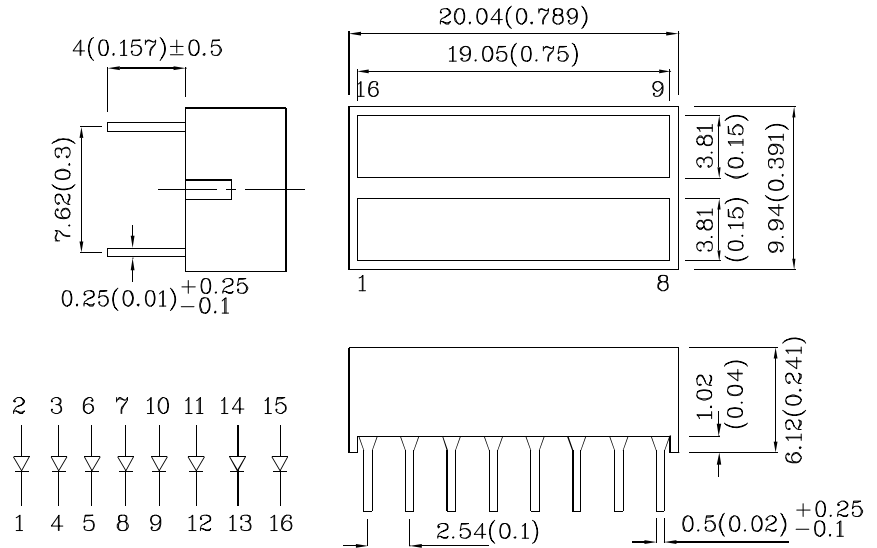


### Features

- Robust package
- Uniform light disbursement
- Ideal for backlighting logos or icons
- Excellent for flush mounting
- RoHS compliant



### Package Schematics



Notes:

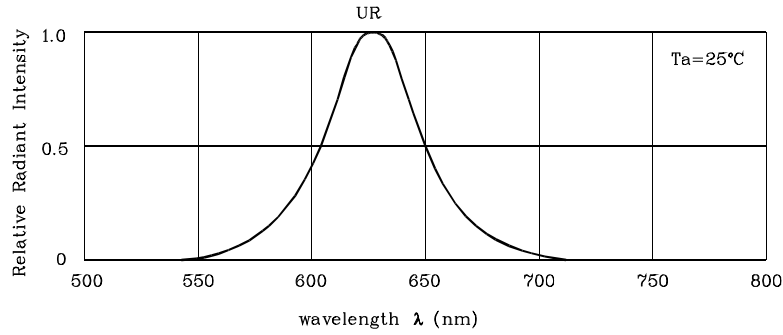
1. All dimensions are in millimeters (inches), Tolerance is ±0.25(0.01") unless otherwise noted.
2. Specifications are subject to change without notice.

Absolute Maximum Ratings (T <sub>A</sub> =25°C)		UR (GaAsP/GaP)	Unit
Reverse Voltage	V <sub>R</sub>	5	V
Forward Current	I <sub>F</sub>	30	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	i <sub>FS</sub>	160	mA
Power Dissipation	P <sub>D</sub>	75	mW
Operating Temperature	T <sub>A</sub>	-40 ~ +85	°C
Storage Temperature	T <sub>stg</sub>	-40 ~ +85	
Lead Solder Temperature [2mm Below Package Base]	260°C For 3-5 Seconds		

Operating Characteristics (T <sub>A</sub> =25°C)		UR (GaAsP/GaP)	Unit
Forward Voltage (Typ.) (I <sub>F</sub> =20mA)	V <sub>F</sub>	2	V
Forward Voltage (Max.) (I <sub>F</sub> =20mA)	V <sub>F</sub>	2.5	V
Reverse Current (Max.) (V <sub>R</sub> =5V)	I <sub>R</sub>	10	µA
Wavelength of Peak Emission CIE127-2007* (Typ.) (I <sub>F</sub> =20mA)	λ <sub>P</sub>	627*	nm
Wavelength of Dominant Emission CIE127-2007* (Typ.) (I <sub>F</sub> =20mA)	λ <sub>D</sub>	617*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I <sub>F</sub> =20mA)	Δλ	45	nm
Capacitance (Typ.) (V <sub>F</sub> =0V, f=1MHz)	C	15	pF

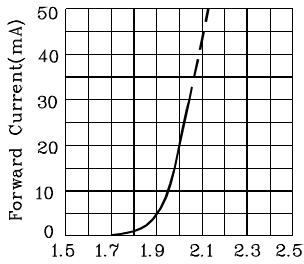
Part Number	Emitting Color	Emitting Material	Luminous Intensity CIE127-2007* (I <sub>F</sub> =20mA) mcd		Wavelength CIE127-2007* nm λ <sub>P</sub>	Lens-color
			min.	typ.		
XEUR2635M	Red	GaAsP/GaP	12 3*	22 7*	627*	White Diffused

\*Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.

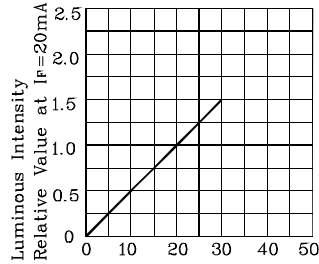


RELATIVE INTENSITY Vs. CIE WAVELENGTH

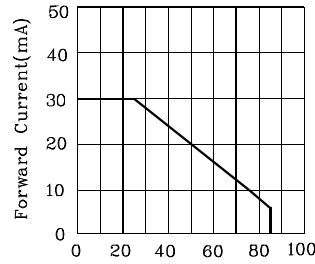
❖ UR



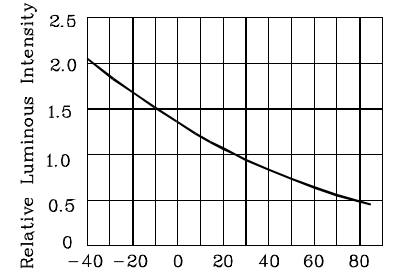
FORWARD CURRENT Vs. FORWARD VOLTAGE



LUMINOUS INTENSITY Vs. FORWARD CURRENT

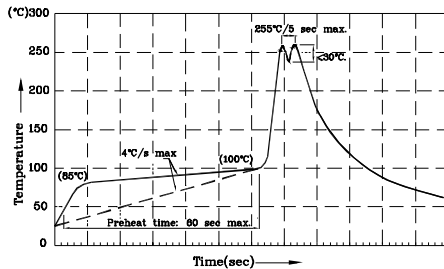


FORWARD CURRENT DERATING CURVE



LUMINOUS INTENSITY Vs. AMBIENT TEMPERATURE

Wave Soldering Profile for Thru-Hole Products (Pb-Free Components)



Notes:

- 1.Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260°C
- 2.Peak wave soldering temperature between 245°C ~ 255°C for 3 sec (5 sec max).
- 3.Do not apply stress to the epoxy resin while the temperature is above 85°C.
- 4.Fixtures should not incur stress on the component when mounting and during soldering process.
- 5.SAC 305 solder alloy is recommended.
- 6.No more than one wave soldering pass.
- 7.During wave soldering, the PCB top-surface temperature should be kept below 105°C.

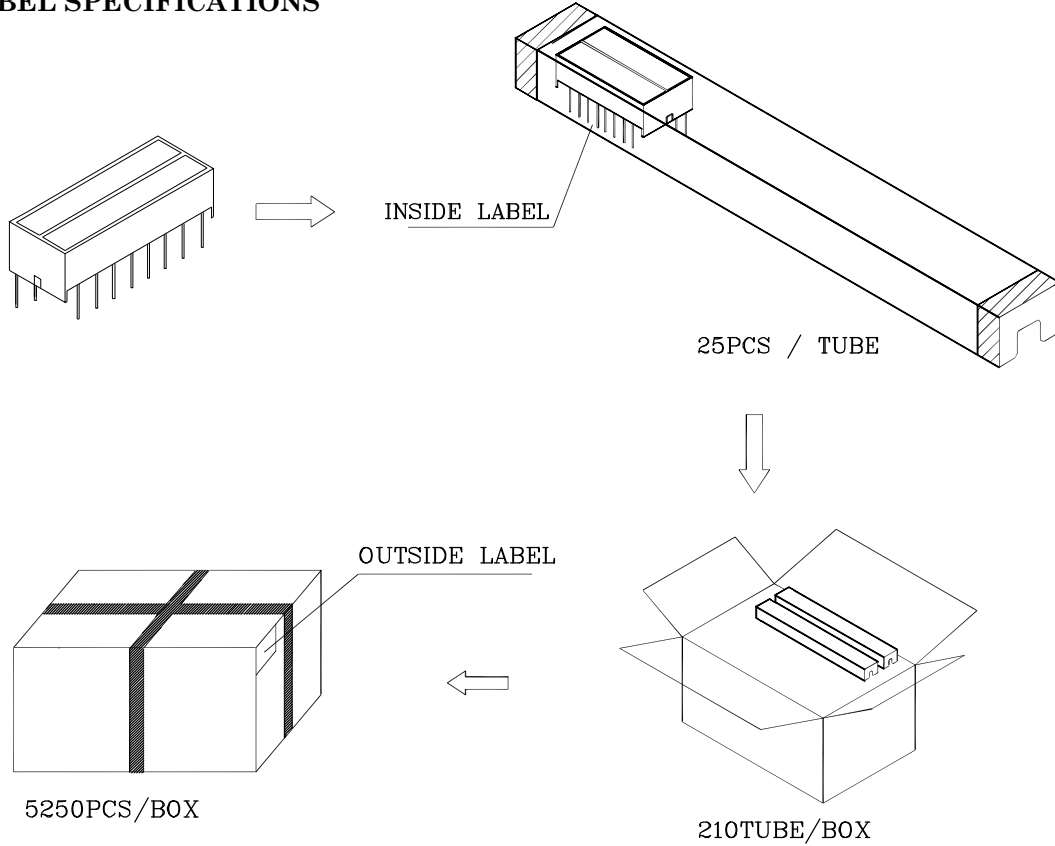
Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

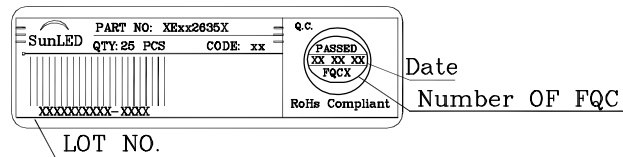
1. Wavelength: +/-1nm
2. Luminous Intensity / Luminous Flux: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

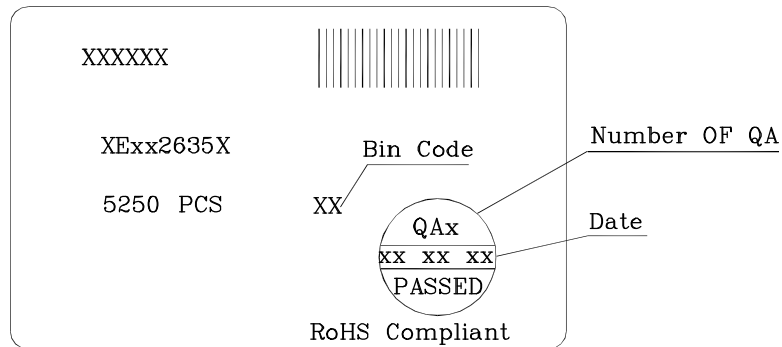
PACKING & LABEL SPECIFICATIONS



Inside Label On IC-tube



Outside Label On Box



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